



ER2000CT~ER2006CT

ISOLATION SUPERFAST RECOVERY RECTIFIER

VOLTAGE 50 to 600 Volts **CURRENT** 20.0 Amperes

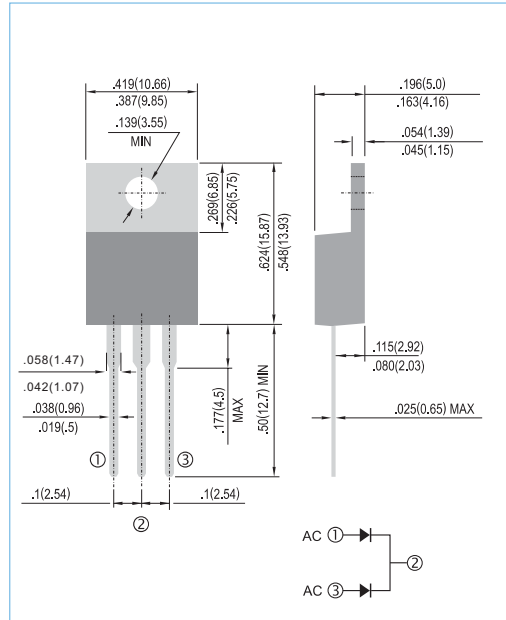
FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-O. Flame Retardant Epoxy Molding Compound.
- Exceeds environmental standards of MIL-S-19500/228
- Low power loss, high efficiency.
- Low forward voltage, high current capability
- High surge capacity.
- Super fast recovery times, high voltage.
- Epitaxial chip construction.
- In compliance with EU RoHS 2002/95/EC directives

MECHANICAL DATA

- Case: TO-220AB Molded plastic
- Terminals: Lead solderable per MIL-STD-750, Method 2026
- Polarity: As marked.
- Standard packaging: Any
- Weight: 0.0655 ounces, 1.859 grams.

TO-220AB Unit: inch (mm)



MAXIMUM RATING AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

PARAMETER	SYMBOL	ER2000CT	ER2001CT	ER2001ACT	ER2002CT	ER2003CT	ER2004CT	ER2006CT	UNITS
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS Voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Current at $T_c=90^\circ\text{C}$	$I_{F(AV)}$	20.0							A
Peak Forward Surge Current : 8.3ms single half sine-wave superimposed on rated load(JEDEC method)	I_{FSM}	150							A
Maximum Forward Voltage at 10A	V_F	0.95			1.3		1.7		V
Maximum DC Reverse Current $T_J=25^\circ\text{C}$ at Rated DC Blocking Voltage $T_J=100^\circ\text{C}$	I_R	1 500							μA
Maximum Reverse Recovery Time (Note 2)	t_{rr}	35			50		100		ns
Typical Junction capacitance (Note 1)	C_J	85							pF
Typical thermal Resistance (Note 3)	$R_{\theta JC}$	3.0							$^\circ\text{C} / \text{W}$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-50 to +150							$^\circ\text{C}$

NOTES:

1. Measured at 1 MHz and applied reverse voltage of 4.0 VDC.
2. Reverse Recovery Test Conditions: $I_F=.5A$, $I_R=1A$, $I_{rr}=.25A$.
3. Both Bonding and Chip structure are available.



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RATING AND CHARACTERISTIC CURVES

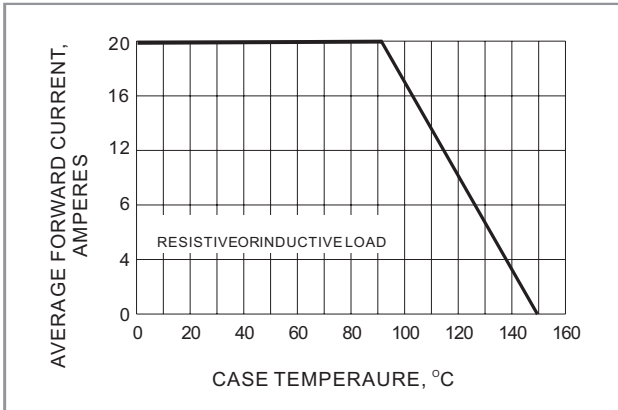


Fig.1- FORWARD CURRENT DERATING CURVE

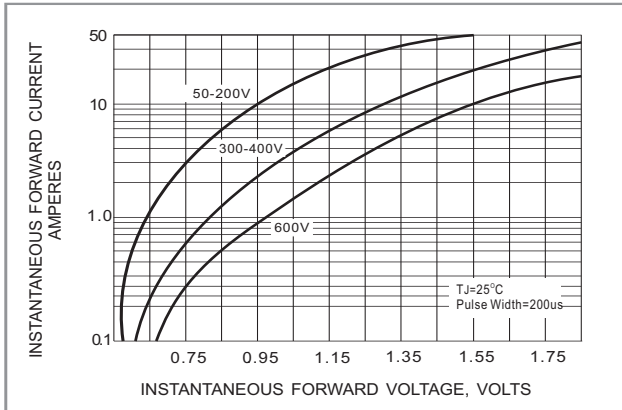


Fig.2- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTIC

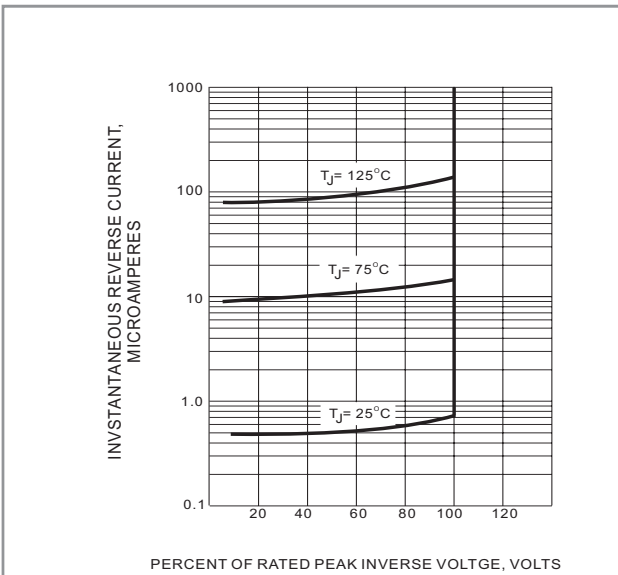


FIG.3 TYPICAL REVERSE CHARACTERISTICS

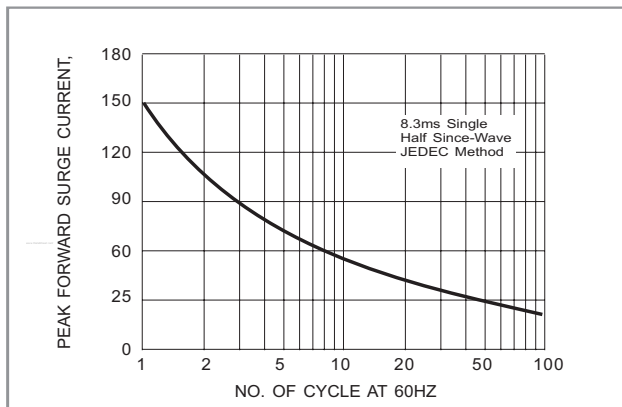


Fig.4- MAXIMUM NON - REPETITIVE SURGE CURRENT

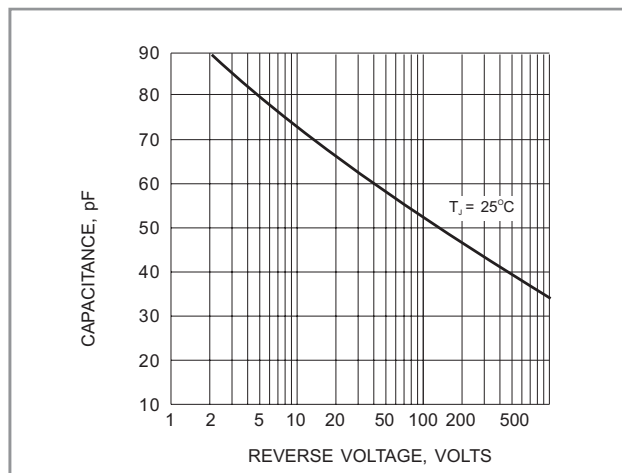


Fig.5- TYPICAL JUNCTION CAPACITANCE